

FUTURE UDIMM DDR4

Introduction

HIKSEMI memory module FUTURE UDIMM is a DDR4 memory module, which is made of high-quality DRAM chips and mature production technology, which makes it more compatible, stable and cost-effective. Can be widely used in PC installations, various high-bandwidth, high-performance system applications.



Features

Cost-effective

Adopt selected IC to make the system run stably and perform better

Good compatibility

Better compatibility, compatible with more products after HIKSEMI optimization.

Ordering Information

Frequency	Capacity	Model	
3200MHz	8GB×2	HSC416U32C3	
	16GB×2	HSC432U32C3	
	32GB×2	HSC464U32C3	
3600MHz	8GB×2	HSC416U36C3	
	16GB×2	HSC432U36C3	
	32GB×2	HSC464U36C3	
4000MHz	8GB×2	HSC416U40C3	
	16GB×2	HSC432U40C3	
	32GB×2	HSC464U40C3	



Please contact the local sales for detailed model information.

Specification

Name	FUTURE UDIMM DDR4			
Capacity	8GB×2	16GB×2	32GB×2	
Interface	DDR4			
frequency	3200/3600/4000MHz			
Pin	288pin			
PCB Size(L×W×H mm)	133.25*31.25*1.4			
Operation temperature	0 °C to 85 °C (32 °F to 185 °F)			
Limited warranty period	Lifetime warranty			
Weight	70g×2			



Revision History

Version	Description	Date
V1.0.0	FUTURE UDIMM DDR4	20240410

Data subject to change without notice.

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The Manual includes instructions for using and managing the Product. Pictures, charts, images and all other information hereinafter are for description and explanation only. The information contained in the Manual is subject to change, without notice, due to firmware updates or other reasons. Please find the latest version of this Manual at the HIKSTORAGE website (www.hiksemitech.com).

